

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2641	(tanaka and kazuhiko).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:02
L2	25	l1 and ((chemical adj mechanical) or CMP or polishing or chemical-mechanical)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:03
L3	1089	(216/52).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:03
L4	440	(216/88).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:03
L5	389	(216/89).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:03
L6	482	(216/93).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:03
L7	2133	(438/692).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:04
L8	338	(156/345.12).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:04

L9	113	(156/345.13).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:04
L10	59	(156/345.14).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:04
L11	384	(216/38).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:04
L12	794	(438/693).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:04
L13	91	((156/345.13).CCLS.) and (slurry or particle\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:05
L14	93	((156/345.13).CCLS.) and (slurry or particle\$1 or abrasive\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:05
S1	26046	chemical adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/02/17 10:35
S2	19881	chemical adj mechanical adj polishing	US-PGPUB; USPAT	OR	OFF	2003/10/28 16:19
S3	5016	(chemical adj mechanical adj polishing).clm.	US-PGPUB; USPAT	OR	OFF	2004/02/17 10:45
S4	872	(216/52).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/27 11:30

S5	380	(216/88).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:03
S6	334	(216/89).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/27 11:31
S7	370	(216/93).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/27 11:31
S8	1637	(438/692).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/27 11:36
S9	6	(("6383332") or ("6419785") or ("6361647")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/27 11:40
S10	258	(156/345.12).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/27 11:40
S11	78	(156/345.13).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/27 11:40
S12	44	(156/345.14).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/27 11:44

S13	357	(216/38).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/27 11:44
S14	675	((chemical adj mechanical adj polishing) and control\$5).clm.	US-PGPUB; USPAT	OR	OFF	2003/10/28 16:15
S15	160	(chemical adj mechanical adj polishing) and (endpoint near3 detect\$3).clm.	US-PGPUB; USPAT	OR	OFF	2003/10/27 11:51
S16	31	((chemical adj mechanical adj polishing) and program\$1).clm.	US-PGPUB; USPAT	OR	OFF	2003/10/27 11:53
S17	82	((chemical adj mechanical adj polishing).clm.) and (endpoint near3 detect\$3).clm.	US-PGPUB; USPAT	OR	OFF	2003/10/27 11:53
S18	634	(438/693).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/27 11:53
S19	83	(chemical adj mechanical adj polishing) and ((particle adj size) near3 measur\$5)	US-PGPUB; USPAT	OR	OFF	2004/02/11 15:55
S20	1945	(chemical adj mechanical adj polishing) and (controller)	US-PGPUB; USPAT	OR	OFF	2003/10/27 13:39
S21	245	(chemical adj mechanical adj polishing) and controller and laser and distribution	US-PGPUB; USPAT	OR	OFF	2003/10/27 13:39
S22	78	(chemical adj mechanical adj polishing) and ((particle adj size) and controller and slurry)	US-PGPUB; USPAT	OR	OFF	2003/10/27 14:15
S23	227	((chemical adj mechanical) or chemical-mechanical) adj (polishing or planarizing)) and (particle adj size adj distribution)	US-PGPUB; USPAT	OR	OFF	2003/10/27 14:18
S24	78	(156/345.13).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/28 09:53
S25	73	((156/345.13).CCLS.) and (polish\$3 or planariz\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/28 09:54

S26	45	((156/345.13).CCLS.) and (polish\$3 or planariz\$5) and (speed or velocity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/02/17 11:23
S27	7	((("6562185") or ("6464824") or ("6261851")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/28 10:15
S28	6	((("5710069") or ("6383332") or ("5846398")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/28 10:18
S29	4	((("5865665") or ("5562530")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/28 13:37
S30	2	("6117779").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/28 13:38
S31	1	2001-121950.NRAN.	DERWENT	OR	OFF	2003/10/28 13:52
S32	91	(chemical adj mechanical adj polishing) and controller and (constant near3 speed)	US-PGPUB; USPAT	OR	OFF	2003/10/28 15:27
S33	13	(chemical adj mechanical adj polishing) and controller and (constant near3 removal)	US-PGPUB; USPAT	OR	OFF	2003/10/28 15:08
S34	2	("5791970").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/28 15:27
S35	1	1998-455870.NRAN.	DERWENT	OR	OFF	2003/10/28 15:27
S36	1	"3028711".PN.	USPAT	OR	OFF	2003/10/28 15:27
S37	1	"5664990".PN.	USPAT	OR	OFF	2003/10/28 15:28
S38	1	"5658185".PN.	USPAT	OR	OFF	2003/10/28 15:28
S39	23	"5791970".URPN.	USPAT	OR	OFF	2003/10/28 15:57

S40	6	("3028711" "3162986" "3500591" "4059929" "5658185" "5664990").PN.	USPAT	OR	OFF	2003/10/28 15:58
S41	72	((156/345.13).CCLS.) and (polish\$3 or planariz\$5) and (speed or velocity or time)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/28 16:00
S42	36	((156/345.13).CCLS.) and (polish\$3 or planariz\$5) and controller	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/28 16:00
S43	86	(chemical adj mechanical adj polishing) and ((particle adj size) near3 (measur\$5 or sensor))	US-PGPUB; USPAT	OR	OFF	2003/10/28 16:07
S44	112	(chemical adj mechanical adj polishing) and (particle adj size) and controller	US-PGPUB; USPAT	OR	OFF	2003/10/28 16:08
S45	150	(chemical adj mechanical adj polishing) and (particle\$1 near2 size) and controller	US-PGPUB; USPAT	OR	OFF	2003/10/28 16:08
S46	695	((chemical adj mechanical adj (planarizing or polishing)) and control\$5) .clm.	US-PGPUB; USPAT	OR	OFF	2003/10/28 16:19
S47	284	((((chemical adj mechanical adj (planarizing or polishing)) and control\$5) .clm.) and (rate near2 (polishing or removal)))	US-PGPUB; USPAT	OR	OFF	2003/10/28 16:20
S48	5099	(chemical adj mechanical adj (planarizing or polishing)).clm.	US-PGPUB; USPAT	OR	OFF	2003/10/28 16:20
S49	124	((chemical adj mechanical adj (planarizing or polishing)).clm.) and (constant with (rate near2 (polishing or removal)))	US-PGPUB; USPAT	OR	OFF	2003/10/28 16:20
S50	2	("6251901").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/29 12:38
S51	12	((("6117779") or ("5865665") or ("5759918") or ("5710069") or ("5846398") or ("6077437"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/29 12:58
S52	594	(chemical adj mechanical adj polishing) and (size with distribution)	US-PGPUB; USPAT	OR	OFF	2004/02/11 15:56

S53	66	(chemical adj mechanical adj polishing) and (size with distribution with (measure\$4 or monitor\$3))	US-PGPUB; USPAT	OR	OFF	2004/02/11 15:59
S54	135	(chemical adj mechanical adj polishing) and (size with distribution with (measure\$4 or monitor\$3 or determin\$3))	US-PGPUB; USPAT	OR	OFF	2004/02/11 16:00
S55	1	((chemical adj mechanical adj polishing) and (size with distribution with (measure\$4 or monitor\$3 or determin\$3))).clm.	US-PGPUB; USPAT	OR	OFF	2004/02/11 16:01
S56	2	("5531861").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/02/17 11:19
S57	3401	(planariz\$3 or polish\$3) and wafer\$1 and slurry and particle\$1 and (monitor\$3 or measur\$3 or determin\$3 or detect\$3 or control\$3) and (size or distribution)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/02/17 10:38
S58	21	((planariz\$3 or polish\$3) and wafer\$1 and slurry and particle\$1 and (monitor\$3 or measur\$3 or determin\$3 or detect\$3 or control\$3) and (size or distribution)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/02/17 10:39
S59	166	((chemical adj mechanical adj polishing) and controller).clm.	US-PGPUB; USPAT	OR	OFF	2004/02/17 10:45
S60	48	((156/345.13).CCLS.) and (slurry and particle\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 14:04
S67	440	(216/88).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/19 16:30
S68	389	(216/89).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/19 16:30

S69	89	(S67 or S68) and control\$4 and (speed or velocity) and measuring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 11:56
S70	189	(S67 or S68) and control\$4 and (speed or velocity) and measur\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/19 16:32
S71	4	(S67 or S68) and (control\$4 and (speed or velocity) and measur\$5).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/19 16:31
S72	38	(S67 or S68) and ((slurry or particle\$1 or abrasive\$1) with (distribution or size) with (measur\$5 or detect\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/19 16:34
S73	113	(156/345.13).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/19 16:34
S74	38	(S67 or S68 or S73) and ((slurry or particle\$1 or abrasive\$1) with (distribution or size) with (measur\$5 or detect\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/19 16:35
S75	296	((chemical adj mechanical) or CMP or chemical-mechanical) and ((control\$4 or adjust\$3) with (speed or velocity)) and ((particle\$1 or abrasive\$1) with (distribution or size\$1) with (control\$3 or measur\$4 or determin\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 12:05
S76	106	((chemical adj mechanical) or CMP or chemical-mechanical) and ((control\$4 or adjust\$3) with (speed or velocity)) and ((particle\$1 or abrasive\$1) with (distribution and size\$1) with (control\$3 or measur\$4 or determin\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 12:16
S77	190	S75 not S76	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 12:05

S78	128	((chemical adj mechanical) or CMP or chemical-mechanical) and ((control\$4 or adjust\$3) with pressure) and ((particle\$1 or abrasive\$1) with (distribution and size\$1) with (control\$3 or measur\$4 or determin\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 12:16
S79	144	((chemical adj mechanical) or CMP or chemical-mechanical) and ((control\$4 or adjust\$3) with (pressure or force)) and ((particle\$1 or abrasive\$1) with (distribution and size\$1) with (control\$3 or measur\$4 or determin\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/20 12:16